



ABSTRACT

This document describes the known exceptions to the functional specifications (advisories).

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1 Functional Advisories

Advisories that affect the device's operation, function, or parametrics.

✓ The check mark indicates that the issue is present in the specified revision.

Errata Number	Rev C
USCI41	✓
USCI47	✓
USCI50	✓

2 Preprogrammed Software Advisories

Advisories that affect factory-programmed software.

✓ The check mark indicates that the issue is present in the specified revision.

The device does not have any errata for this category.

3 Debug Only Advisories

Advisories that affect only debug operation.

✓ The check mark indicates that the issue is present in the specified revision.

The device does not have any errata for this category.

4 Fixed by Compiler Advisories

Advisories that are resolved by compiler workaround. Refer to each advisory for the IDE and compiler versions with a workaround.

✓ The check mark indicates that the issue is present in the specified revision.

The device does not have any errata for this category.

Refer to the following MSP430 compiler documentation for more details about the CPU bugs workarounds.

TI MSP430 Compiler Tools (Code Composer Studio IDE)

- [MSP430 Optimizing C/C++ Compiler](#): Check the --silicon_errata option
- [MSP430 Assembly Language Tools](#)

MSP430 GNU Compiler (MSP430-GCC)

- [MSP430 GCC Options](#): Check -msilicon-errata= and -msilicon-errata-warn= options
- [MSP430 GCC User's Guide](#)

IAR Embedded Workbench

- [IAR workarounds for msp430 hardware issues](#)

5 Nomenclature, Package Symbolization, and Revision Identification

The revision of the device can be identified by the revision letter on the [Package Markings](#) or by the [HW_ID](#) located inside the TLV structure of the device.

5.1 Device Nomenclature

To designate the stages in the product development cycle, TI assigns prefixes to the part numbers of all MSP MCU devices. Each MSP MCU commercial family member has one of two prefixes: MSP or XMS. These prefixes represent evolutionary stages of product development from engineering prototypes (XMS) through fully qualified production devices (MSP).

XMS – Experimental device that is not necessarily representative of the final device's electrical specifications

MSP – Fully qualified production device

Support tool naming prefixes:

X: Development-support product that has not yet completed Texas Instruments internal qualification testing.

null: Fully-qualified development-support product.

XMS devices and X development-support tools are shipped against the following disclaimer:

"Developmental product is intended for internal evaluation purposes."

MSP devices have been characterized fully, and the quality and reliability of the device have been demonstrated fully. TI's standard warranty applies.

Predictions show that prototype devices (XMS) have a greater failure rate than the standard production devices. TI recommends that these devices not be used in any production system because their expected end-use failure rate still is undefined. Only qualified production devices are to be used.

TI device nomenclature also includes a suffix with the device family name. This suffix indicates the temperature range, package type, and distribution format.

5.2 Package Markings

RHB32

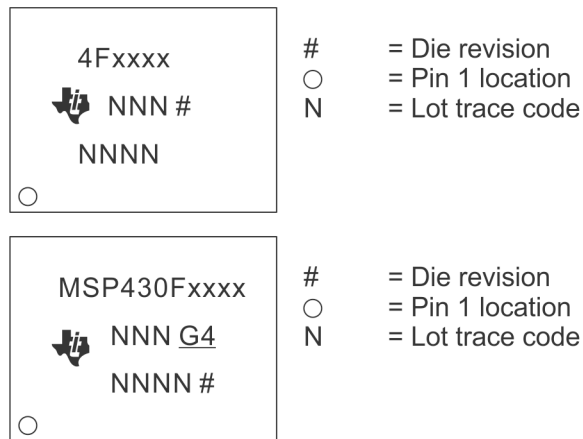
QFN (RHB), 32 Pin



= Die revision
○ = Pin 1 location
N = Lot trace code

PW28

TSSOP (PW), 28 Pin



5.3 Memory-Mapped Hardware Revision (TLV Structure)

This device does not support reading the hardware revision from memory.

Further guidance on how to locate the TLV structure and read out the HW_ID can be found in the device User's Guide.

6 Advisory Descriptions

USCI41	<i>USCI Module</i>
Category	Functional
Function	UCBUSY bit of eUSCIA module might not work reliable when device is in SPI mode.
Description	When eUSCIA is configured in SPI mode, the UCBUSY bit might get stuck to 1 or start toggling after transmission is completed. This happens in all four combinations of Clock Phase and Clock Polarity options (UCAxCTLW0.UCCKPH & UCAxCTLW0.UCCKPL bits) as well as in Master and Slave mode. There is no data loss or corruption. However the UCBUSY cannot be used in its intended function to check if transmission is completed. Because the UCBUSY bit is stuck to 1 or toggles, the clock request stays enabled and this adds additional current consumption in low power mode operation.
Workaround	For correct functional implementation check on transmit or receive interrupt flag UCTXIFG/UCRXIFG instead of UCBUSY to know if the UCAxTXBUF buffer is empty or ready for the next complete character. To reduce the additional current it is recommended to either reset the SPI module (UCAxCTLW0.UCSWRST) in the UCBxCTLW0 or send a dummy byte 0x00 after the intended SPI transmission is completed.
USCI47	<i>USCI Module</i>
Category	Functional
Function	eUSCI SPI slave with clock phase UCCKPH = 1
Description	The eUSCI SPI operates incorrectly under the following conditions: 1. The eUSCI_A or eUSCI_B module is configured as a SPI slave with clock phase mode UCCKPH = 1 AND 2. The SPI clock pin is not at the appropriate idle level (low for UCCKPL = 0, high for UCCKPL = 1) when the UCSWRST bit in the UCxxCTLW0 register is cleared. If both of the above conditions are satisfied, then the following will occur: eUSCI_A: the SPI will not be able to receive a byte (UCAxRXBUF will not be filled and UCRXIFG will not be set) and SPI slave output data will be wrong (first bit will be missed and data will be shifted). eUSCI_B: the SPI receives data correctly but the SPI slave output data will be wrong (first byte will be duplicated or replaced by second byte).
Workaround	Use clock phase mode UCCKPH = 0 for MSP SPI slave if allowed by the application. OR The SPI master must set the clock pin at the appropriate idle level (low for UCCKPL = 0, high for UCCKPL = 1) before SPI slave is reset (UCSWRST bit is cleared). OR For eUSCI_A: to detect communication failure condition where UCRXIFG is not set, check both UCRXIFG and UCTXIFG. If UCTXIFG is set twice but UCRXIFG is not set, reset the

MSP SPI slave by setting and then clearing the UCSWRST bit, and inform the SPI master to resend the data.

USCI50***USCI Module***

Category

Functional

Function

Data may not be transmitted correctly from the eUSCI when operating in SPI 4-pin master mode with UCSTEM = 0

Description

When the eUSCI is used in SPI 4-pin master mode with UCSTEM = 0 (STE pin used as an input to prevent conflicts with other SPI masters), data that is moved into UCxTXBUF while the UCxSTE input is in the inactive state may not be transmitted correctly. If the eUSCI is used with UCSTEM = 1 (STE pin used to output an enable signal), data is transmitted correctly.

Workaround

When using the STE pin in conflict prevention mode (UCSTEM = 0), only move data into UCxTXBUF when UCxSTE is in the active state. If an active transfer is aborted by UCxSTE transitioning to the master-inactive state, the data must be rewritten into UCxTXBUF to be transferred when UCxSTE transitions back to the master-active state.

7 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from March 9, 2021 to May 11, 2021

Page

- Changed the document format and structure; updated the numbering format for tables, figures, and cross references throughout the document.....5

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